

IN THE SPECIFICATION

Please amend the Specification starting at p. 2, line 5 as follows:

This application is a continuation-in-part application of allowed US patent application "Microelectronic Device Package with an Integral Window, Peterson and Watson, of Serial of Application No. 09/571,335, filed 05/06/2000 (now US 6,384,473), which is incorporated herein by reference. This application is related to allowed US Patent Application 09/572,720 to Peterson and Conley, "Pre-Release Plastic Packaging of MEMS and IMEMS Devices", which is incorporated herein by reference. This application is also related to co-pending application, "Single Level Microelectronic Device Package with an Integral Window", to Peterson and Watson, Attorney Docket No. SD-7121, which is incorporated herein by reference.